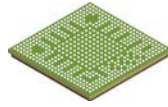


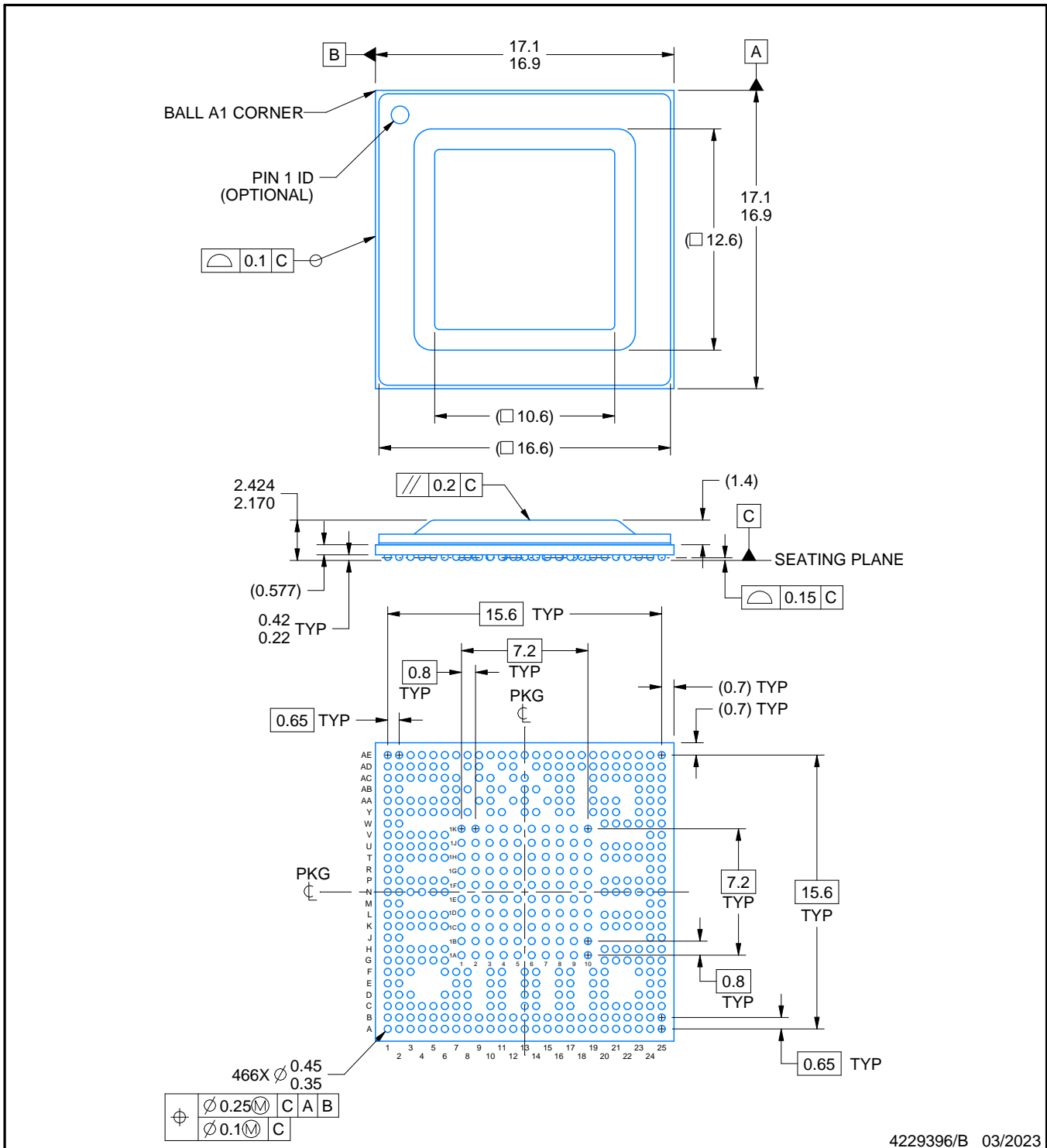
# AMH0466A



# PACKAGE OUTLINE

FCBGA - 2.504 mm max height

BALL GRID ARRAY



**NOTES:**

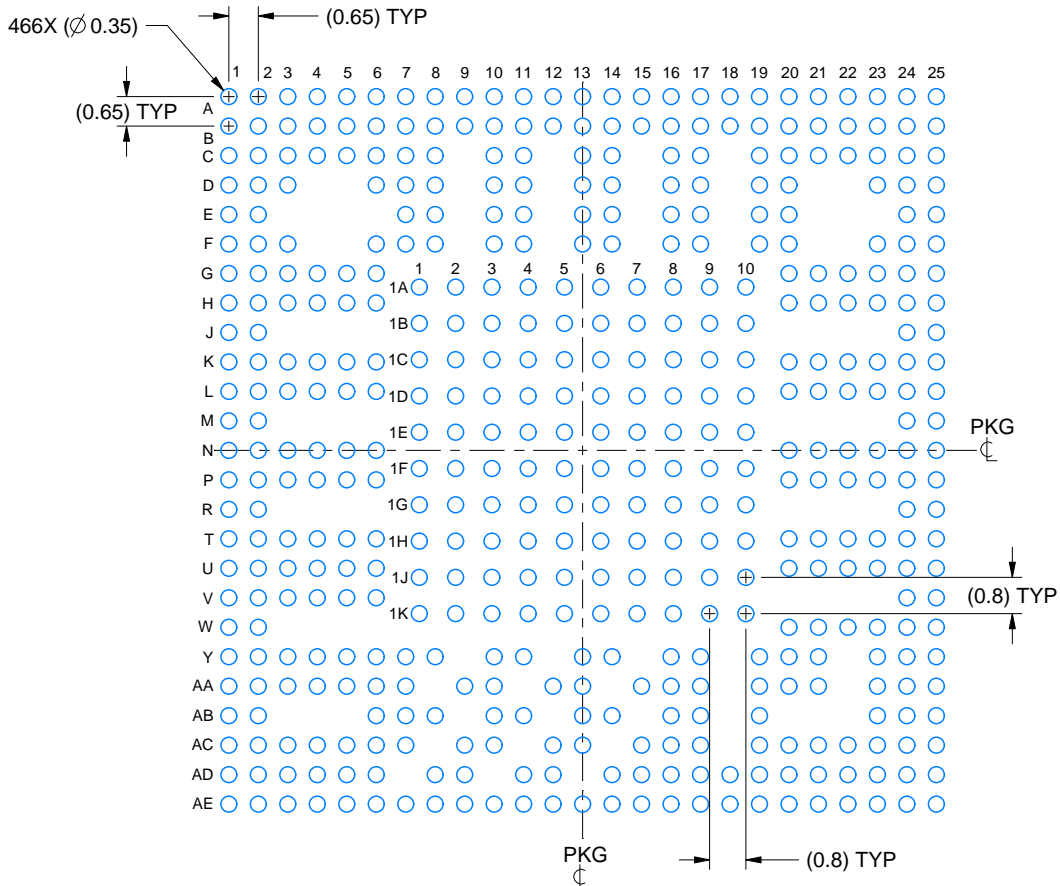
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

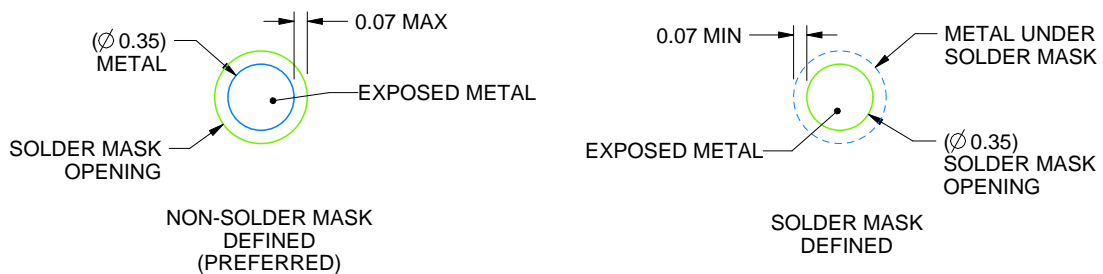
AMH0466A

FCBGA - 2.504 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:6X



SOLDER MASK DETAILS  
NOT TO SCALE

4229396/B 03/2023

NOTES: (continued)

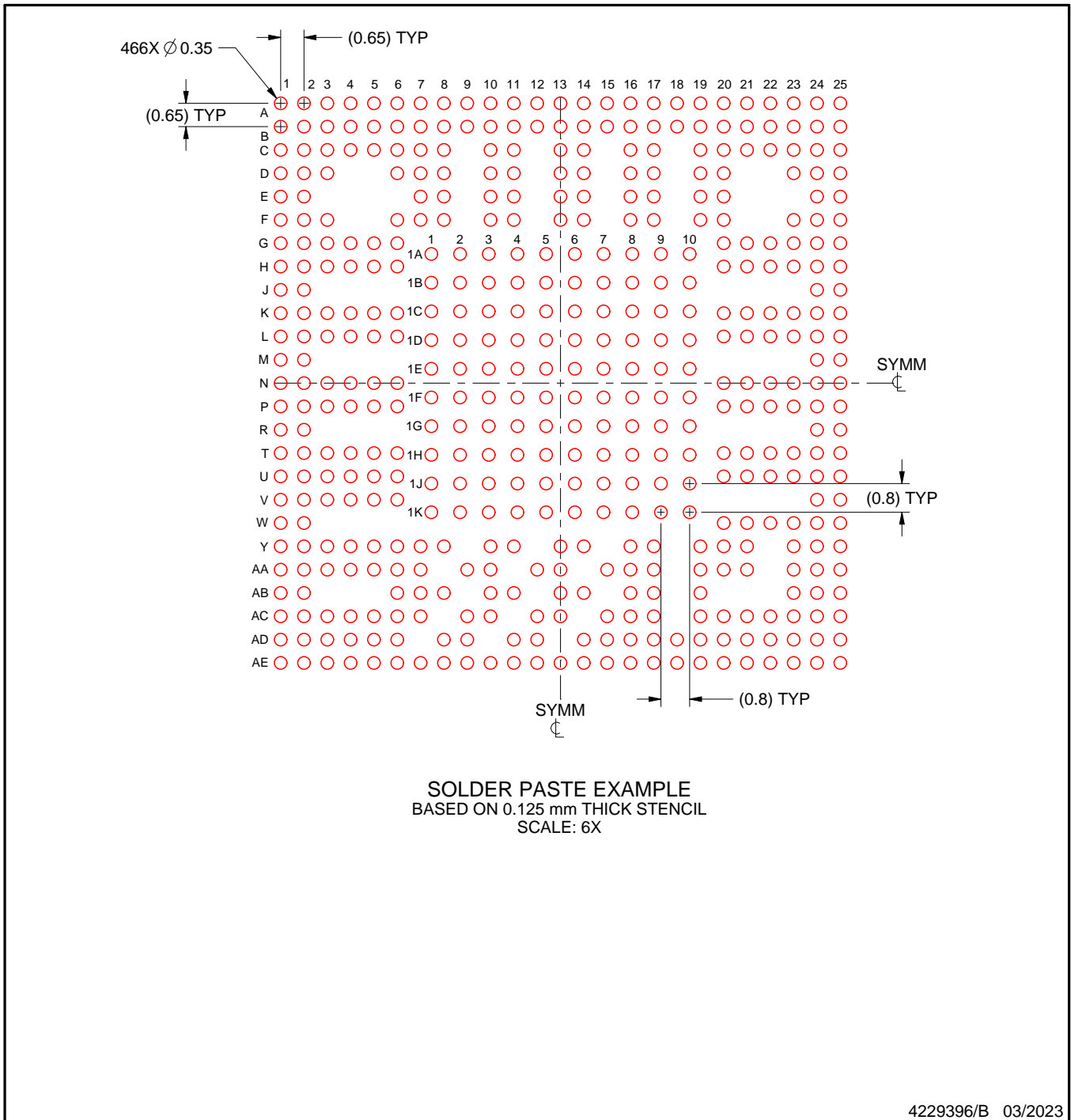
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 ([www.ti.com/lit/spru811](http://www.ti.com/lit/spru811)).

# EXAMPLE STENCIL DESIGN

AMH0466A

FCBGA - 2.504 mm max height

BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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